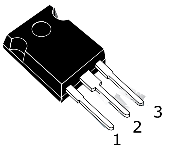
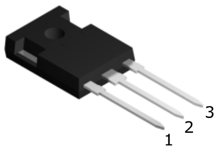
STGW75M65DF2, STGWA75M65DF2

Trench gate field-stop IGBT, M series 650 V, 75 A low-loss in TO-247 and TO-247 long leads packages

Datasheet - production data

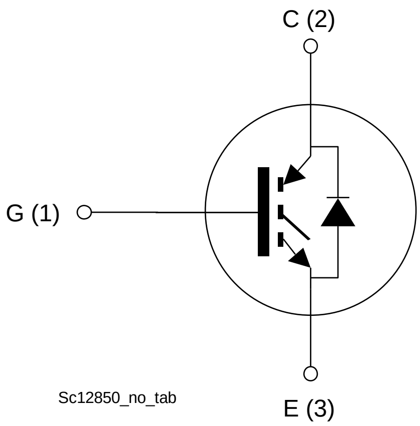


TO-247



TO-247 long leads

Figure 1: Internal schematic diagram



Features

- 6 µs of short-circuit withstand time
- $V_{CE(sat)}$ = 1.65 V (typ.) @ I_C = 75 A
- Tight parameter distribution
- Safer paralleling
- Positive $V_{CE(sat)}$ temperature coefficient
- Low thermal resistance
- Soft and very fast recovery antiparallel diode
- Maximum junction temperature: T_J = 175 °C

Applications

- Motor control
- UPS
- PFC
- General purpose inverter

Description

These devices are IGBTs developed using an advanced proprietary trench gate field-stop structure. The devices are part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where low-loss and short-circuit functionality are essential. Furthermore, the positive $V_{CE(sat)}$ temperature coefficient and tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGW75M65DF2	G75M65DF2	TO-247	Tube
STGWA75M65DF2		TO-247 long leads	

This is information on a product in full production.

Contents

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage (V_{GE} = 0 V)	650	V
I_C(1)	Continuous collector current at T_C = 25 °C	120	A
I_C	Continuous collector current at T_C = 100 °C	75	A
I_{CP}(2)	Pulsed collector current	225	A
V_{GE}	Gate-emitter voltage	±20	V
I_F(1)	Continuous forward current at T_C = 25 °C	120	A
I_F	Continuous forward current at T_C = 100 °C	75	A
I_{FP}(2)	Pulsed forward current	225	A
P_{TOT}	Total dissipation at T_C = 25 °C	468	W
T_{STG}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature range	- 55 to 175	°C

Notes:

(1)Current level is limited by bond wires

(2)Pulse width limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.32	°C/W
R_{thJC}	Thermal resistance junction-case diode	0.74	°C/W
R_{thJA}	Thermal resistance junction-ambient	50	°C/W

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	V_{GE} = 0 V, I_C = 250 µA	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	V_{GE} = 15 V, I_C = 75 A		1.65	2.1	V
		V_{GE} = 15 V, I_C = 75 A, T_J = 125 °C		1.95		
		V_{GE} = 15 V, I_C = 75 A, T_J = 175 °C		2.1		
V_F	Forward on-voltage	I_F = 75 A		2	2.85	V
		I_F =75 A, T_J = 125 °C		1.75		
		I_F = 75 A, T_J = 175 °C		1.6		
$V_{GE(th)}$	Gate threshold voltage	V_{CE} = V_{GE}, I_C = 2 mA	5	6	7	V
I_{CES}	Collector cut-off current	V_{GE} = 0 V, V_{CE} = 650 V			25	µA
I_{GES}	Gate-emitter leakage current	V_{CE} = 0 V, V_{GE}= ± 20 V			±250	µA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	V_{CE} = 25 V, f = 1 MHz, V_{GE} = 0 V	-	6290	-	pF
C_{oes}	Output capacitance		-	390	-	
C_{res}	Reverse transfer capacitance		-	136	-	
Q_g	Total gate charge	V_{CC} = 520 V, I_C = 75 A, V_{GE} = 0 to 15 V (see *Figure 30: " Gate charge test circuit"*)	-	225	-	nC
Q_{ge}	Gate-emitter charge		-	53	-	
Q_{gc}	Gate-collector charge		-	87	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 75 A, V_{GE} = 15 V, R_G = 3.3 Ω (see *Figure 29: " Test circuit for inductive load switching"*)		47	-	ns
t_r	Current rise time			22.4	-	ns
$(di/dt)_{on}$	Turn-on current slope			2680	-	A/µs
$t_{d(off)}$	Turn-off-delay time			125	-	ns
t_f	Current fall time			93	-	ns
E_{on} (1)	Turn-on switching energy			0.69	-	mJ
E_{off} (2)	Turn-off switching energy			2.54	-	mJ
E_{ts}	Total switching energy			3.23	-	mJ
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 75 A, V_{GE} = 15 V, R_G = 3.3 Ω T_J = 175 °C (see *Figure 29: " Test circuit for inductive load switching"*)		48	-	ns
t_r	Current rise time			25	-	ns
$(di/dt)_{on}$	Turn-on current slope			2420	-	A/µs
$t_{d(off)}$	Turn-off-delay time			125	-	ns
t_f	Current fall time			167	-	ns
E_{on} (1)	Turn-on switching energy			2.17	-	mJ
E_{off} (2)	Turn-off switching energy			3.45	-	mJ
E_{ts}	Total switching energy			5.62	-	mJ
t_{sc}	Short-circuit withstand time	$V_{CC} \leq$ 400 V, V_{GE} = 13 V, $T_{Jstart} \leq$ 150 °C	10		-	µs
		$V_{CC} \leq$ 400 V, V_{GE} = 15 V, $T_{Jstart} \leq$ 150 °C	6			

Notes:

(1)Including the reverse recovery of the diode.

(2)Including the tail of the collector current.

Table 7: Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	I_F = 75 A, V_R = 400 V, V_{GE} = 15 V, di/dt = 1000 A/µs (see *Figure 29: " Test circuit for inductive load switching"*)	-	165	-	ns
Q_{rr}	Reverse recovery charge		-	1.72	-	µC
I_{rrm}	Reverse recovery current		-	25	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	750	-	A/µs
E_{rr}	Reverse recovery energy		-	289	-	µJ
t_{rr}	Reverse recovery time	I_F = 75 A, V_R = 400 V, V_{GE} = 15 V, di/dt = 1000 A/µs, T_J = 175 °C (see *Figure 29: " Test circuit for inductive load switching"*)	-	256	-	ns
Q_{rr}	Reverse recovery charge		-	6.85	-	µC
I_{rrm}	Reverse recovery current		-	48	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	300	-	A/µs
E_{rr}	Reverse recovery energy		-	1033	-	µJ

2.1 Electrical characteristics (curves)

Figure 2: Power dissipation vs. case temperature

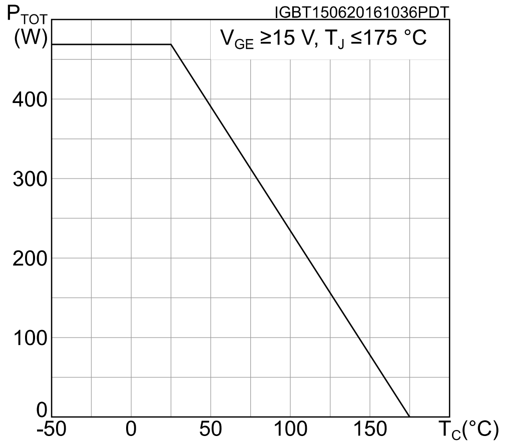


Figure 3: Collector current vs. case temperature

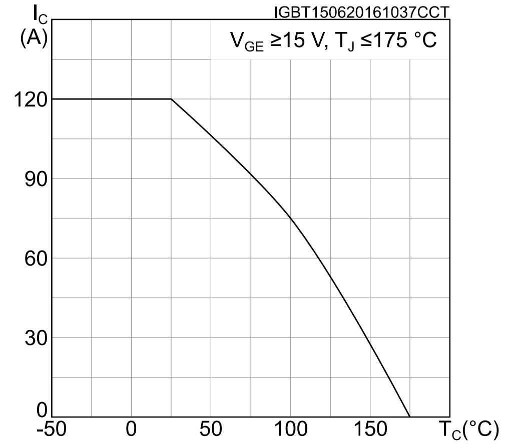


Figure 4: Output characteristics (T_J = 25 °C)

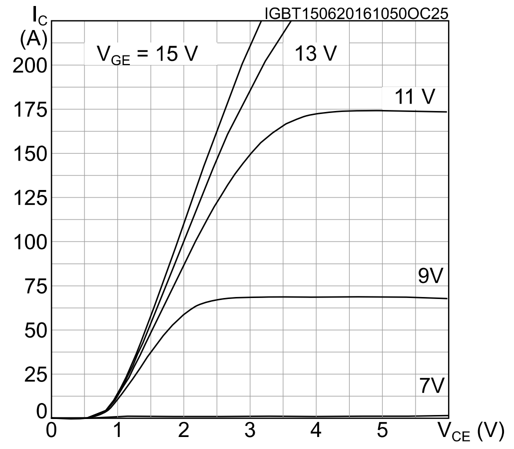


Figure 5: Output characteristics (T_J = 175 °C)

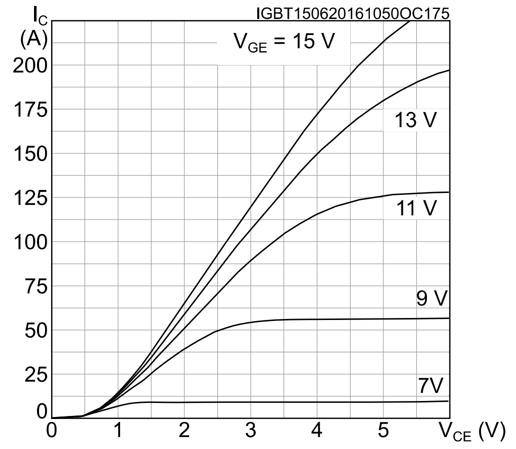


Figure 6: $V_{CE(sat)}$ vs. junction temperature

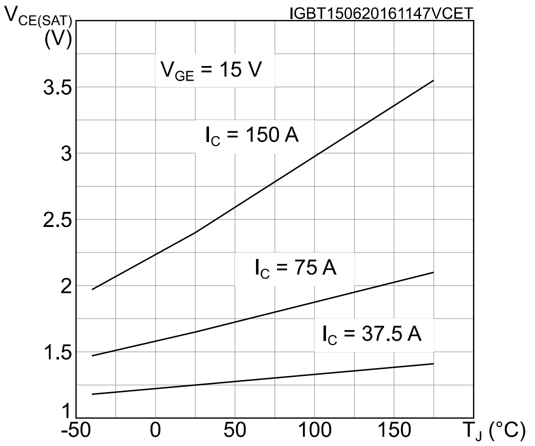


Figure 7: $V_{CE(sat)}$ vs. collector current

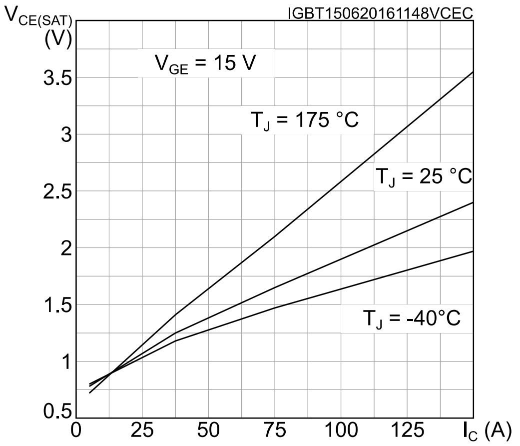


Figure 8: Collector current vs. switching frequency

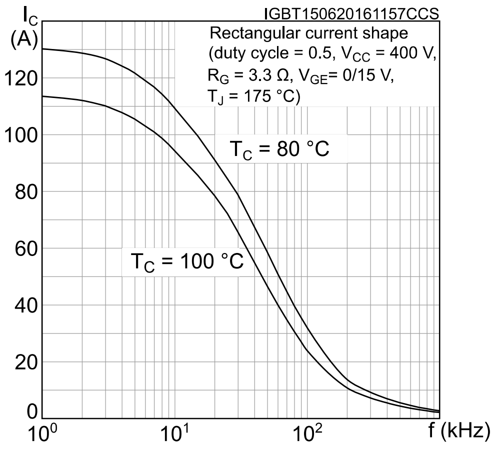


Figure 9: Forward bias safe operating area

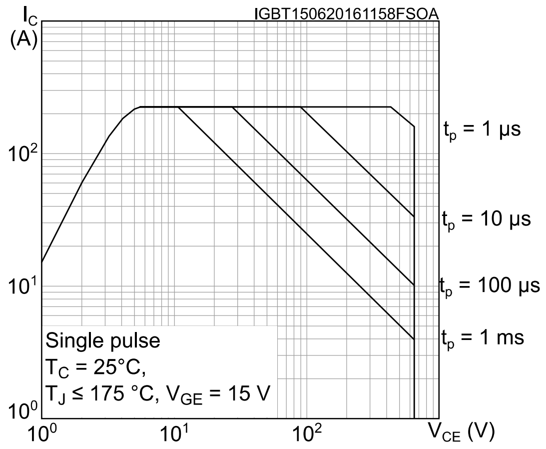


Figure 10: Transfer characteristics

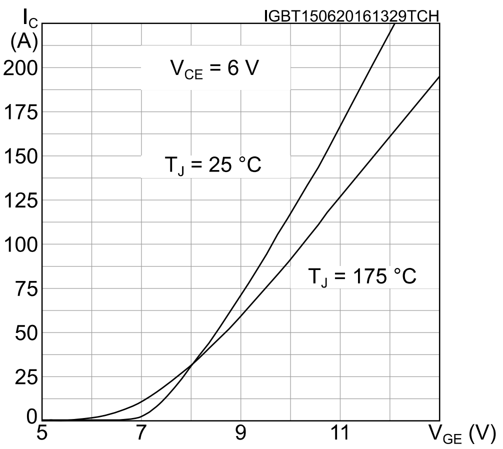


Figure 11: Diode V_F vs. forward current

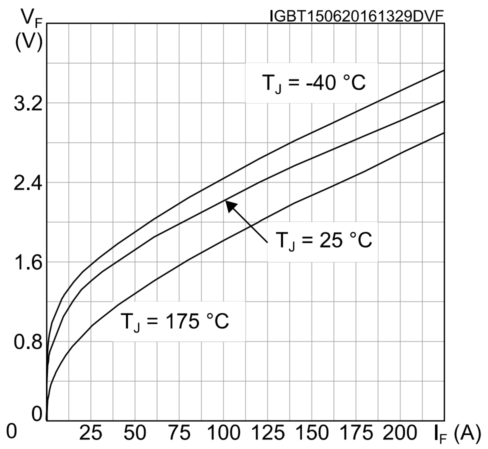


Figure 12: Normalized $V_{GE(th)}$ vs. junction temperature

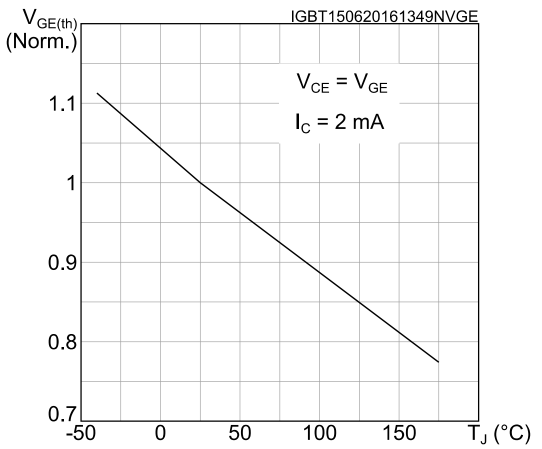


Figure 13: Normalized $V_{(BR)CES}$ vs. junction temperature

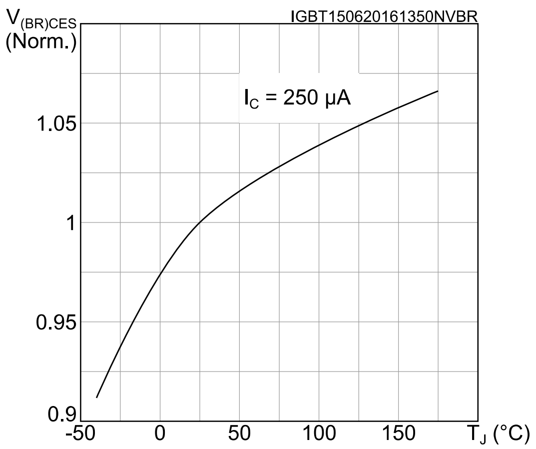


Figure 14: Capacitance variations

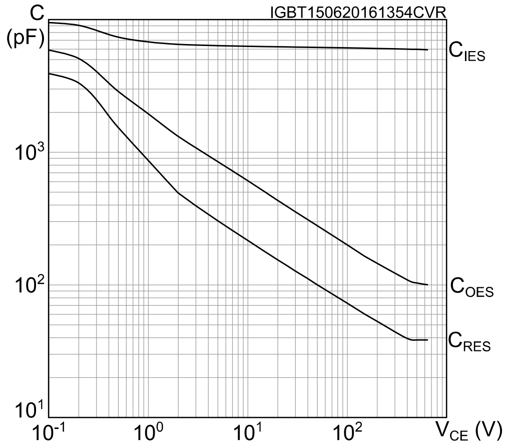


Figure 15: Gate charge vs. gate-emitter voltage

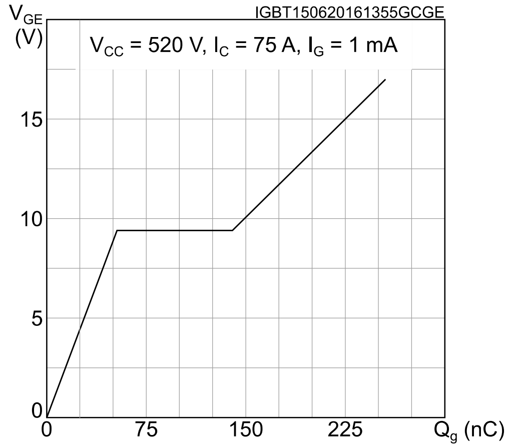


Figure 16: Switching energy vs. collector current

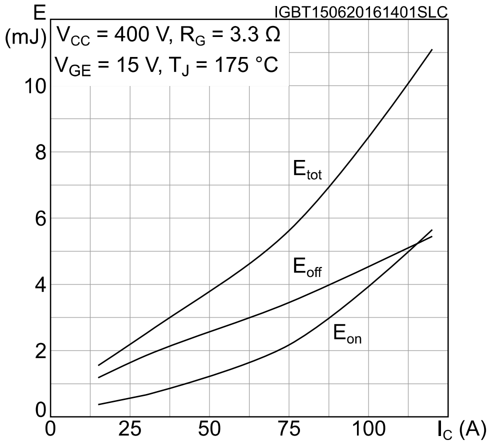


Figure 17: Switching energy vs. gate resistance

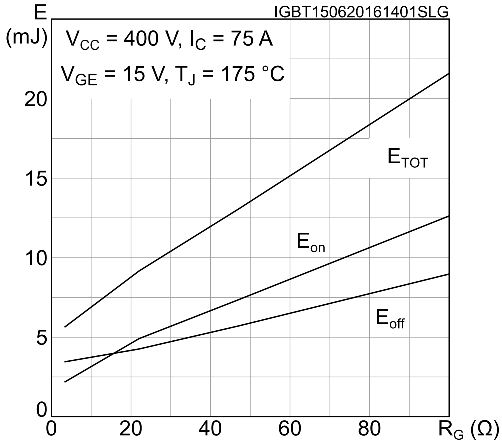


Figure 18: Switching energy vs. temperature

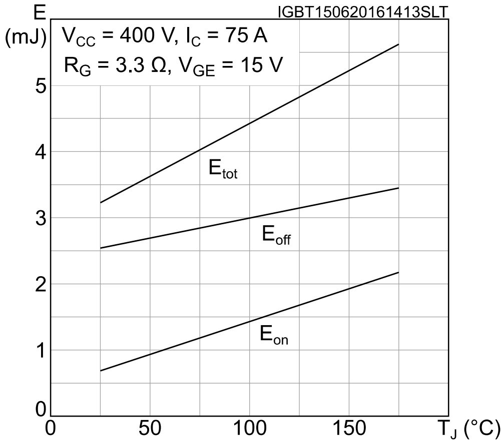


Figure 19: Switching energy vs. collector emitter voltage

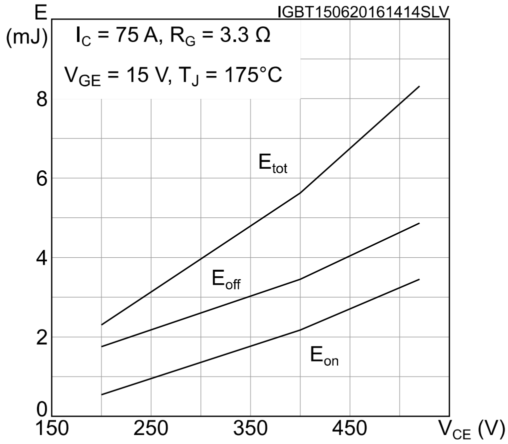


Figure 20: Short-circuit time and current vs. V_{GE}

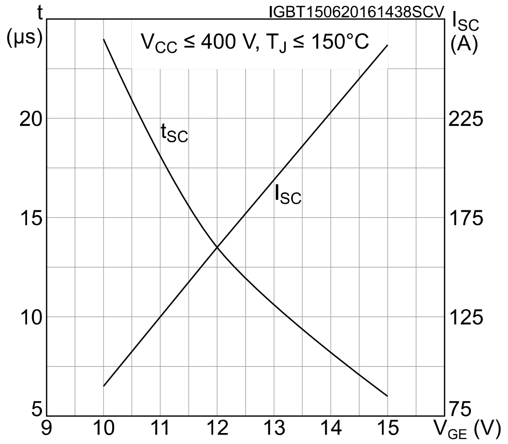


Figure 21: Switching times vs. collector current

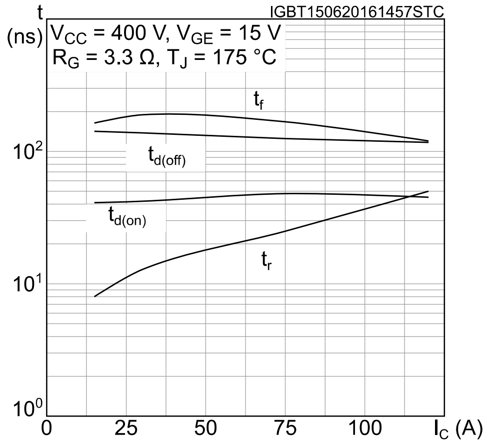


Figure 22: Switching times vs. gate resistance

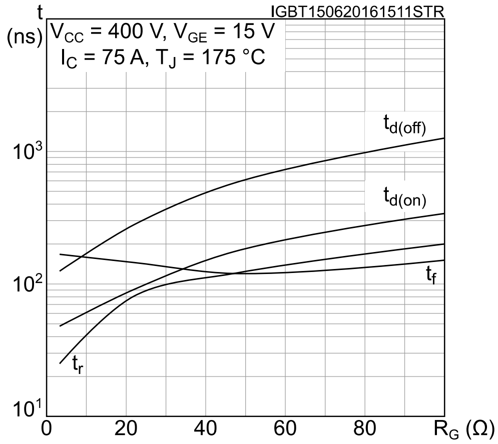


Figure 23: Reverse recovery current vs. diode current slope

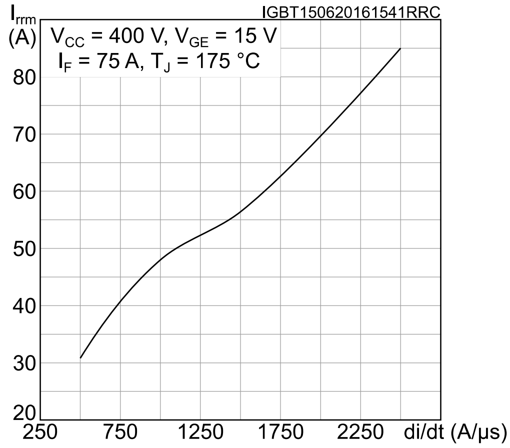


Figure 24: Reverse recovery time vs. diode current slope

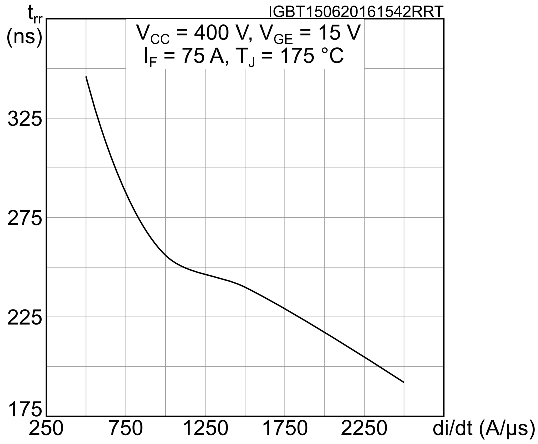


Figure 25: Reverse recovery charge vs. diode current slope

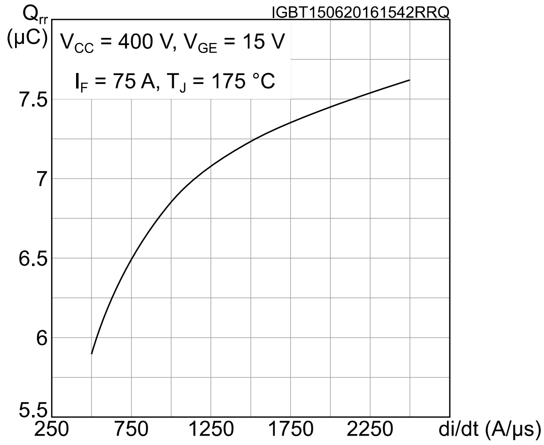


Figure 26: Reverse recovery energy vs. diode current slope

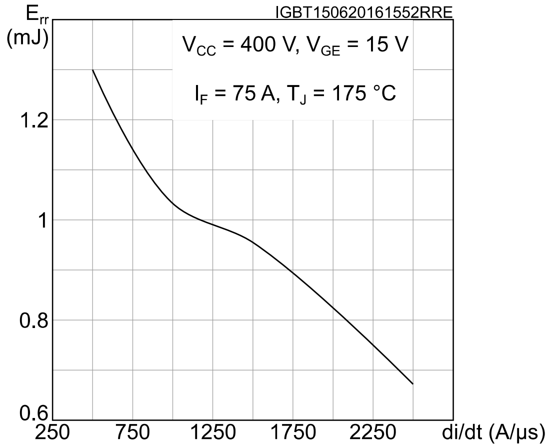


Figure 27: Thermal impedance for IGBT

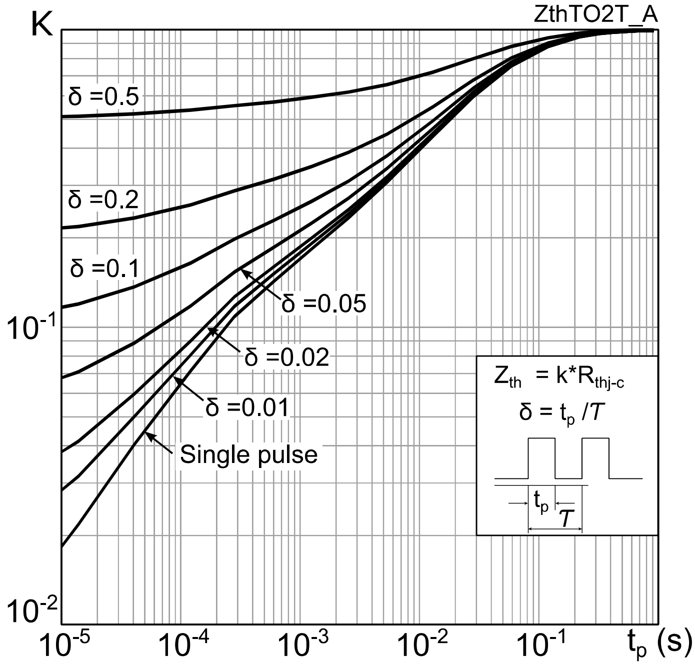
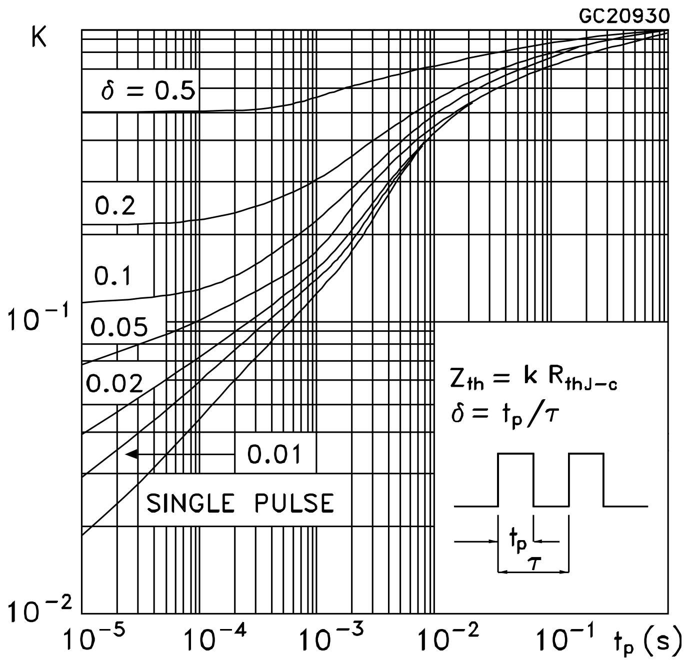


Figure 28: Thermal impedance for diode



3 Test circuits

Figure 29: Test circuit for inductive load switching

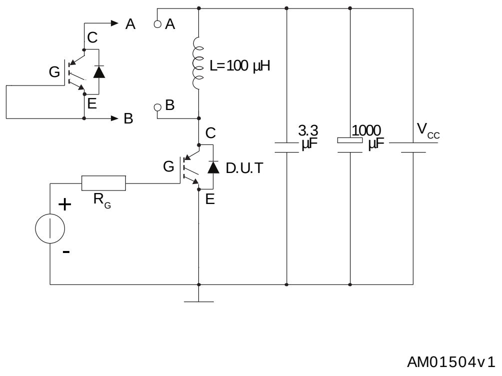


Figure 30: Gate charge test circuit

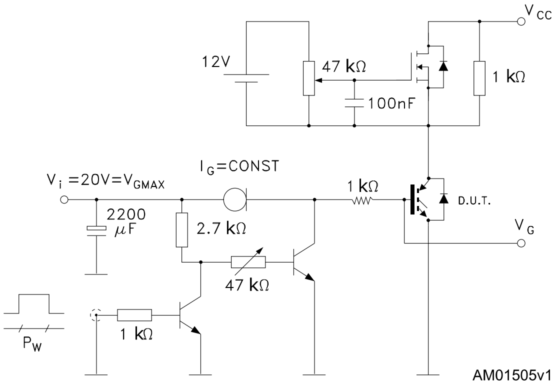


Figure 31: Switching waveform

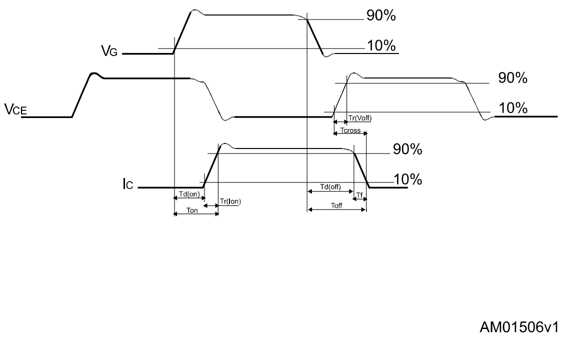
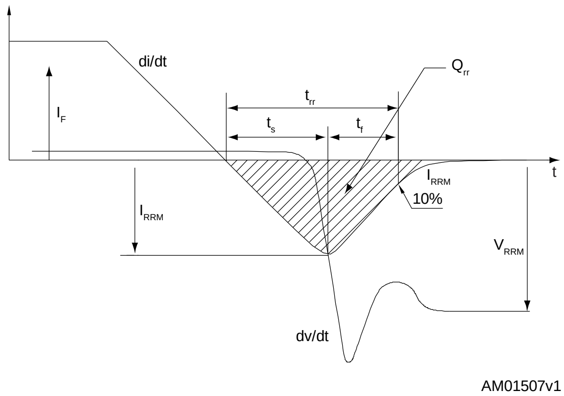


Figure 32: Diode reverse recovery waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

4.1 TO-247 package information

Figure 33: TO-247 package outline

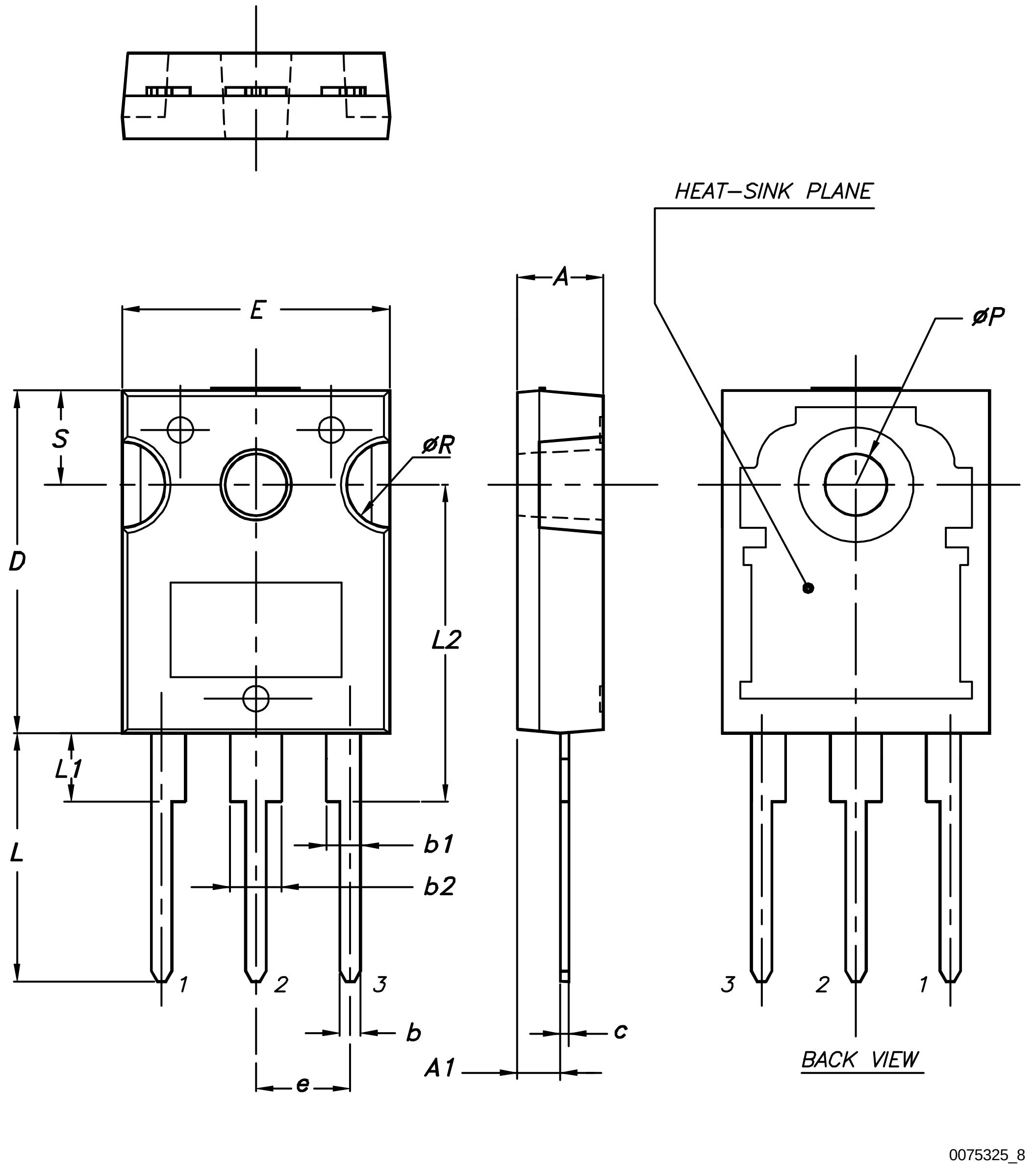


Table 8: TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

4.2 TO-247 long leads package information

Figure 34: TO-247 long leads package outline

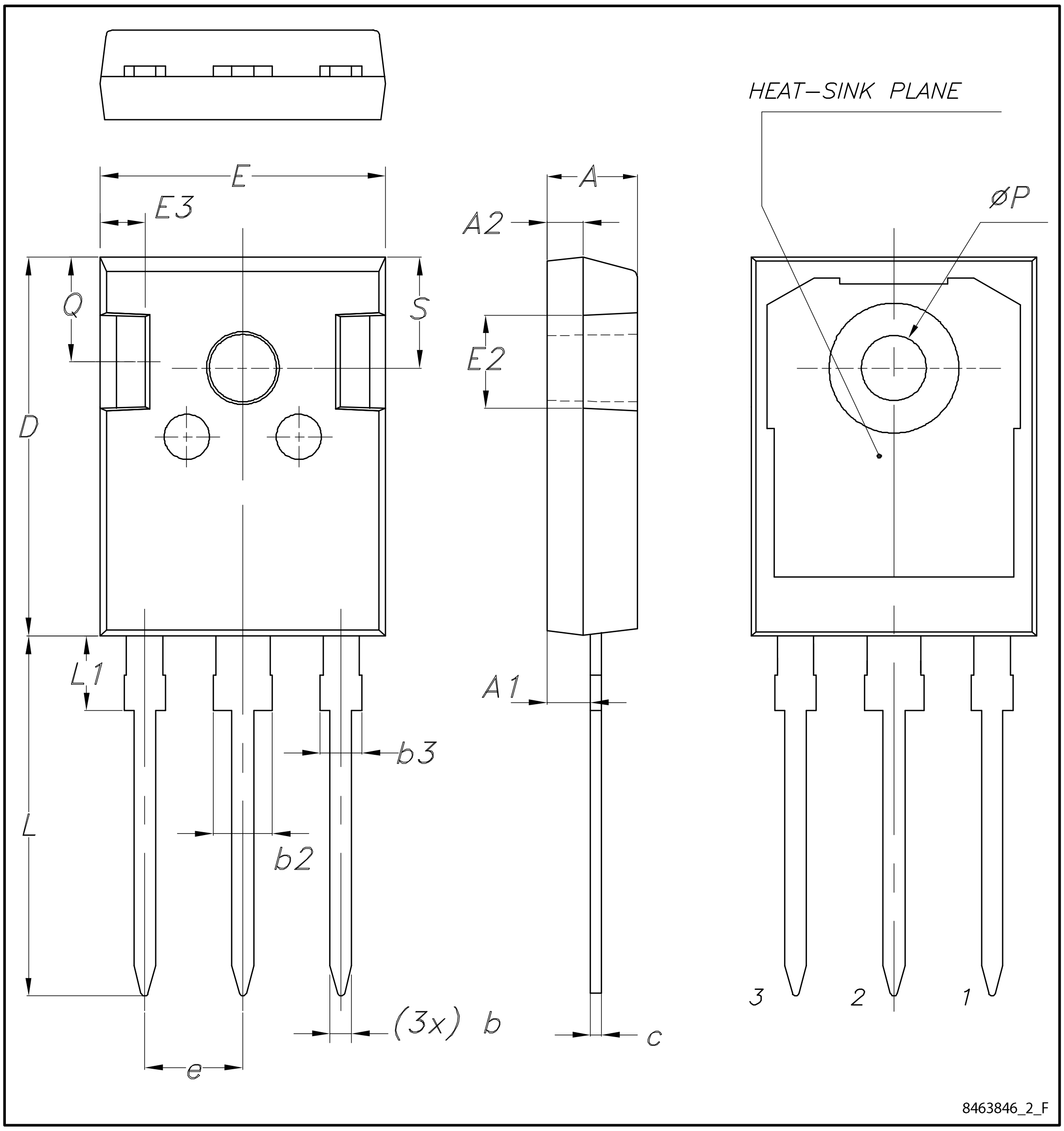


Table 9: TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
02-Dec-2015	1	First release.
15-Jun-2016	2	Inserted device in TO-247 and document updated accordingly. Inserted *Section 2.1: "Electrical characteristics (curves)".* Document status promoted from preliminary to production data. Minor text changes.
03-May-2017	3	Modified: title, features and application on cover page. Modified *Table 4: "Static characteristics"*, *Table 7: "Diode switching characteristics (inductive load)"* and *Figure 13: "Normalized $V_{(BR)CES}$ vs. junction temperature "*. Minor text changes.

单击下面可查看定价，库存，交付和生命周期等信息

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